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FOR IMMEDIATE RELEASE

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PEMTRON to Demonstrate Precision Inspection Systems for Semiconductor & Electronics Manufacturing at NEPCON Nagoya

September 2024 — PEMTRON, an inspection equipment developer and supplier, is pleased to announce its participation in NEPCON Nagoya 2024, where it will showcase its cutting-edge equipment designed for precision inspection in semiconductor and electronics manufacturing. From October 23-25, visitors to PEMTRON's booth will experience demonstrations of the JUPITER 3D X-ray Inspection System, POSEIDON Wafer Warpage Measurement and FC-BGA Bump Inspection System, APOLLON Package Inspection System, and the 8800WIR Wafer Inspection System.

The JUPITER 3D X-ray Inspection System offers both 3D and 2D capabilities through advanced PCT reconstruction-based processing. Equipped with a high-resolution optical camera and integrated with PEMTRON's proven AOI defect detection algorithms, JUPITER provides manufacturers with an exceptional tool for comprehensive in-line inspection and process quality analysis. Its seamless integration with SPI and AOI systems enables data sharing, delivering valuable insights into the production process and enhancing overall efficiency.



The POSEIDON System offers a cutting-edge solution for wafer warpage measurement and FC-BGA bump inspection. Leveraging 3D data, POSEIDON precisely measures warpage, flatness, and coplanarity, while its high-resolution imaging identifies fine defects like missing bumps, bridging, and more. Designed to support advanced processes such as wire bonding and Micro LED applications, POSEIDON delivers swift, accurate mapping and profiling data essential for high-precision manufacturing.



PEMTRON's APOLLON Package Inspection System is engineered for real-time defect detection across a wide variety of packages, including BGA, LGA, QFN, QFP, CSP, and SOP. With its automated reporting capabilities, APOLLON

significantly enhances production efficiency and minimizes downtime, ensuring high-quality results for manufacturers.

Also on display will be the 8800WIR Wafer Inspection System, which utilizes 2D and 3D imaging technologies to inspect micro bumps and other types of wafer components. This system plays a critical role in detecting and addressing quality issues early in the semiconductor manufacturing process, ensuring optimal production quality.

Join PEMTRON at NEPCON Nagoya 2024 for live demonstrations and discover how these revolutionary systems are shaping the future of semiconductor and electronics manufacturing. For more information about PEMTRON, please visit www.pemtron.com.

About PEMTRON

Based on 3D precision measurement and vision source technology, PEMTRON develops equipment used in various fields such as SMT, Automotive Field, Lead Tab, Semiconductor, and supplies Soldering Inspection equipment (3D SPI), 3D Mounting Inspection equipment (3D AOI, MOI), Conformal Coating Inspection equipment (TROI-8800 CI), Bottom Head Inspection equipment (Eagle 8800TH), Top & Bottom Double Sided Simultaneous Inspection equipment (Eagle 8800TWIN), Automated X-Ray SMD Counter (MERCURY), Wafer Sawing Before/After 3D Inspection equipment (8800 WI/WIR), Wire Bonding 3D Inspection & MEMS Auto Inspection equipment (ZEUS), Package AVI equipment (APOLLON), Memory Module / SSD Auto Inspection equipment (MARS), FC-BGA, FCP-CSP Inspection equipment (POSEIDON-S), Scale Sorter Of FC-BGA Products (8800 FI), Bump Metal Mask Inspection equipment (8800 MI), PCB Appearance Inspection equipment (8800 AI) and Lead Tab Process/Inspection equipment (Hawk 7300).